

WHAT IS CLAIMED IS:

1. A substrate treating apparatus comprising:
 - an equipment front end module for carrying in a substrate for a treatment and carrying out the substrate which has been treated;
 - 5 a processing module for processing the substrate;
 - a transfer chamber for carrying in and out the substrate to the process module and controlling an oxygen concentration; and
 - a loadlock chamber positioned between the equipment front and end module and the transfer chamber for providing a path for the substrate to be moved and
 - 10 controlling an oxygen concentration;
- wherein the loadlock chamber comprises:
 - a carry in chamber for providing a path for the substrate carried in from the equipment front and end module to the transfer chamber; and
 - a carry out chamber for providing a path for the substrate carried out
 - 15 from the transfer chamber to the equipment front and end module;
- wherein the carry in chamber and the carry out chamber are arranged separately from each other;
- wherein the carry in chamber is provided with a carry in sensor for detecting an oxygen concentration within the carry in chamber;
- 20 wherein the carry out chamber is provided with a carry out sensor for detecting an oxygen concentration within the carry out chamber;
- wherein the transfer chamber is provided with a sensor for detecting an oxygen concentration within the transfer chamber; and
- wherein an oxygen concentration of the carry in chamber and the carry out
- 25 chamber is controlled independently.

2. The substrate treating apparatus of claim 1, wherein the carry in chamber is connected to a carry in supply line for supplying an inert gas and a carry in exhaust line for exhausting a gas.

5

3. The substrate treating apparatus of claim 2, wherein a supply of the inert gas or an exhaust of the gas is controlled depending on an oxygen concentration detected from the carry in sensor.

10 4. The substrate treating apparatus of claim 1, wherein the carry out chamber is connected to a carry out supply line for supplying an inert gas and a carry out exhaust line for exhausting a gas.

15 5. The substrate treating apparatus of claim 4, wherein a supply of the inert gas or an exhaust of the gas is controlled depending on an oxygen concentration detected from the carry out sensor.

20 6. The substrate treating apparatus of claim 1, wherein the transfer chamber is connected to a supply line for supplying an inert gas and an exhaust line for exhausting a gas, wherein a supply of the inert gas or an exhaust of the gas is controlled depending on an oxygen concentration detected from the sensor.

25 7. The substrate treating apparatus of claim 1 further comprising a door for opening and closing a path where the substrate is transferred between the equipment front and end module and the loadlock chamber, or between the loadlock

chamber and the transfer chamber, or between the transfer chamber and the processing module

8. The substrate treating apparatus of claim 7, wherein the door
5 comprises:

a shield in which a discharge hole is formed to discharge an inert gas toward the outer surface of the path when the path is opened and provided as a plate form; and

a driver for moving the shield.
10

9. The substrate treating apparatus of claim 8, wherein a plurality of the discharge holes is formed to the widthwise direction of the path corresponding to the width of the path.

10. The substrate treating apparatus of claim 9, wherein the shield
15 comprises a distribution space connected to the plurality of the discharge holes therein.

11. The substrate treating apparatus of claim 8, wherein the path is
20 arranged vertically, respectively, and wherein the door comprises a first door for opening and closing a top path and a second door for opening and closing a bottom path.

12. The substrate treating apparatus of claim 11, wherein the first door moves to a top when the top path is opened and the second door moves to a bottom when the bottom path is opened.

- 5 13. The substrate treating apparatus of claim 12, wherein a first discharge hole of the first door and a second discharge hole of the second door are formed in a position deviate from an array where the two doors are arranged vertically to each other when viewed from a lateral side.